TITLE: SEMICONDUCTOR SUBSTRATES INCLUDING I/O REDISTRIBUTION USING WIRE BONDS AND ANISOTROPICALLY CONDUCTIVE FILM, METHODS OF FABRICATION AND ASSEMBLIES INCLUDING SAME

Inventor: Lua et al. Docket No.: 2269-5709US

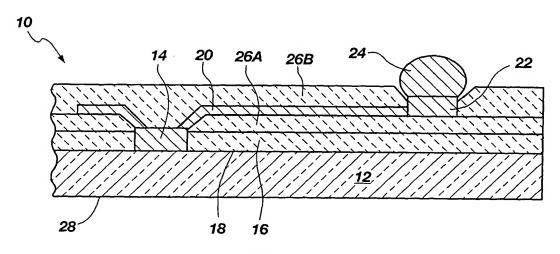
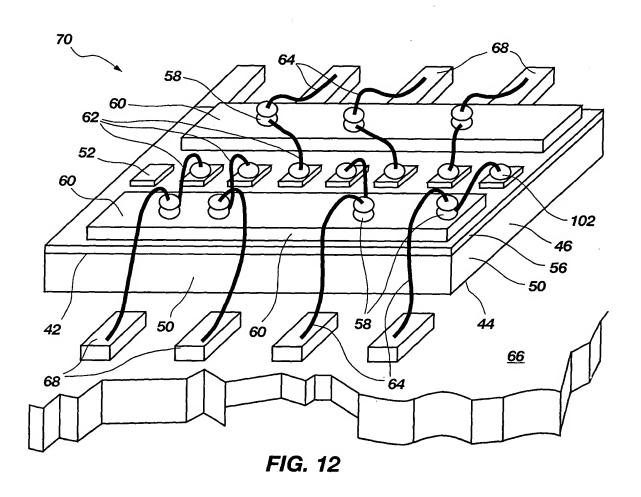


FIG. 1 (PRIOR ART)



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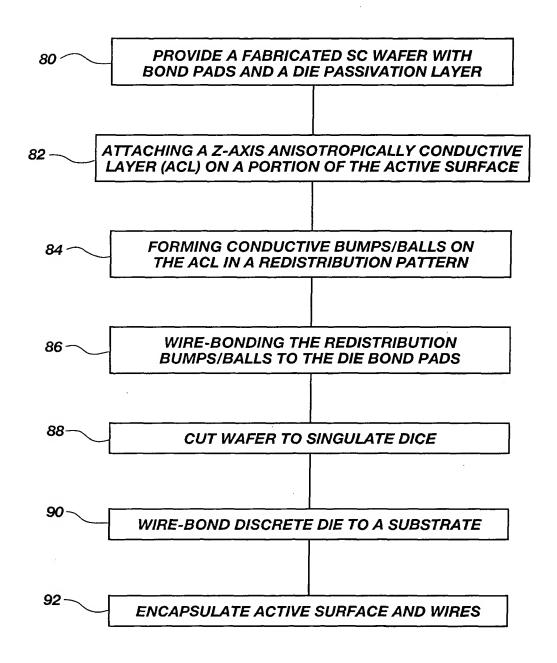
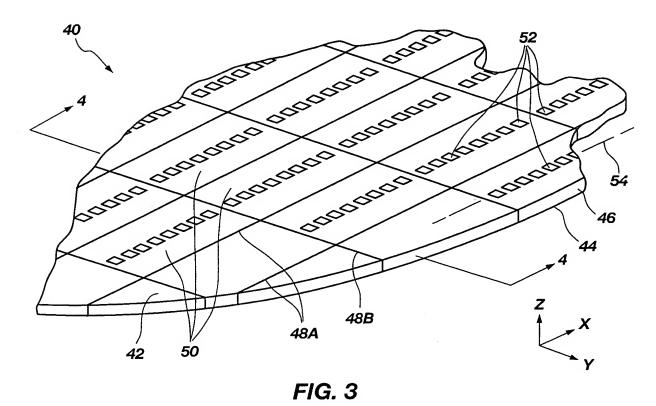


FIG. 2

TITLE: SEMICONDUCTOR SUBSTRATES INCLUDING I/O REDISTRIBUTION USING WIRE BONDS AND ANISOTROPICALLY CONDUCTIVE FILM, METHODS OF FABRICATION AND ASSEMBLIES INCLUDING SAME





48A

FIG. 4

TITLE: SEMICONDUCTOR SUBSTRATES INCLUDING I/O REDISTRIBUTION USING WIRE BONDS AND ANISOTROPICALLY CONDUCTIVE FILM, METHODS OF FABRICATION AND ASSEMBLIES INCLUDING SAME

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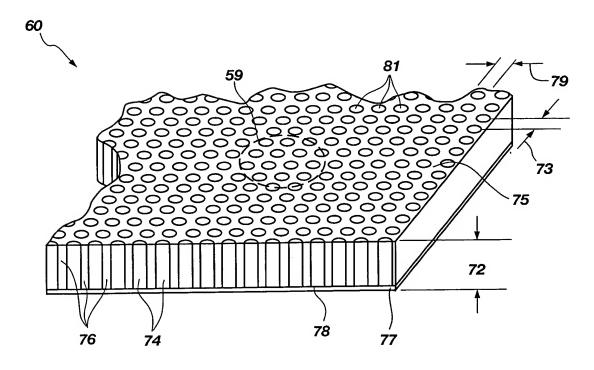


FIG. 5

TITLE: SEMICONDUCTOR SUBSTRATES INCLUDING I/O REDISTRIBUTION USING WIRE BONDS AND ANISOTROPICALLY CONDUCTIVE FILM, METHODS OF FABRICATION AND ASSEMBLIES INCLUDING SAME



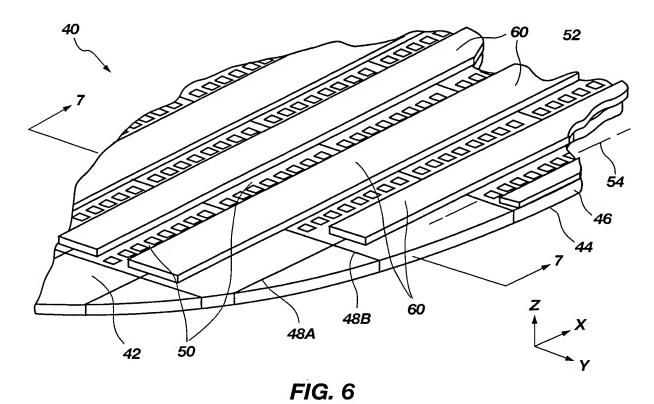
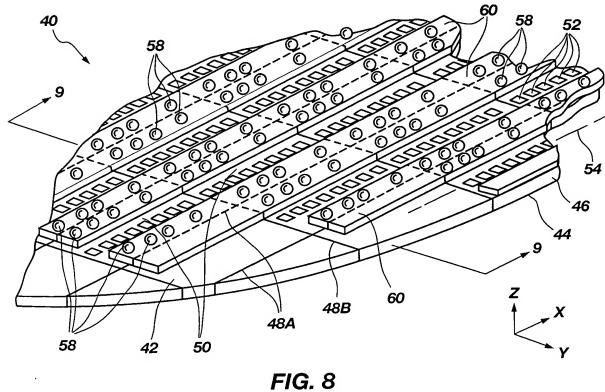


FIG. 7

TITLE: SEMICONDUCTOR SUBSTRATES INCLUDING I/O REDISTRIBUTION USING WIRE BONDS AND ANISOTROPICALLY CONDUCTIVE FILM, METHODS OF FABRICATION AND ASSEMBLIES INCLUDING SAME





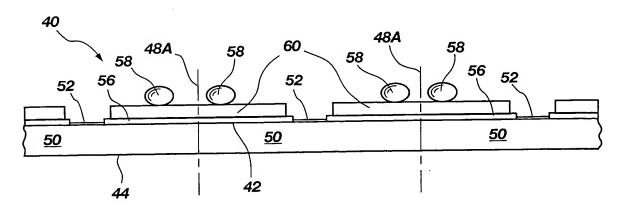


FIG. 9

TITLE: SEMICONDUCTOR SUBSTRATES INCLUDING I/O REDISTRIBUTION USING WIRE BONDS AND ANISOTROPICALLY CONDUCTIVE FILM, METHODS OF FABRICATION AND ASSEMBLIES INCLUDING SAME

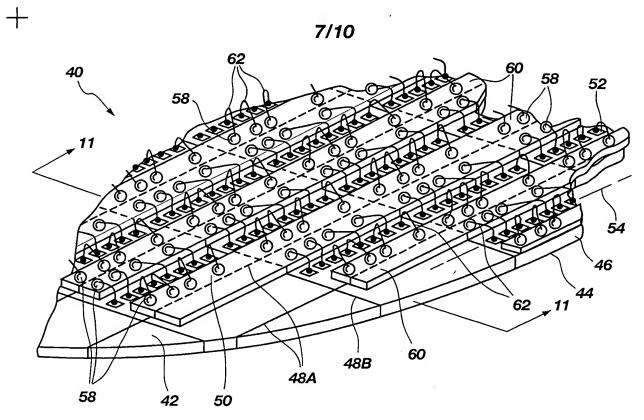


FIG. 10

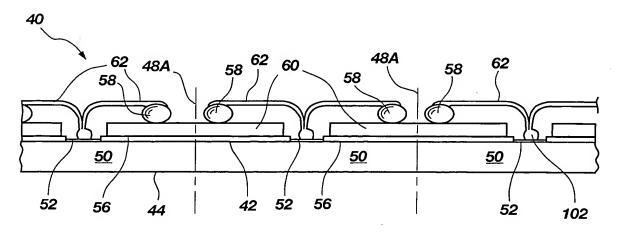


FIG. 11

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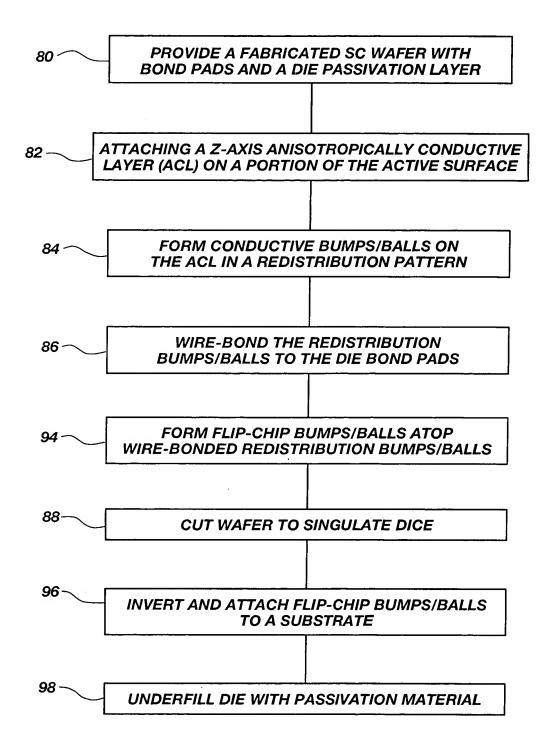


FIG. 13

TITLE: SEMICONDUCTOR SUBSTRATES INCLUDING I/O REDISTRIBUTION USING WIRE BONDS AND ANISOTROPICALLY CONDUCTIVE FILM, METHODS OF FABRICATION AND ASSEMBLIES INCLUDING SAME

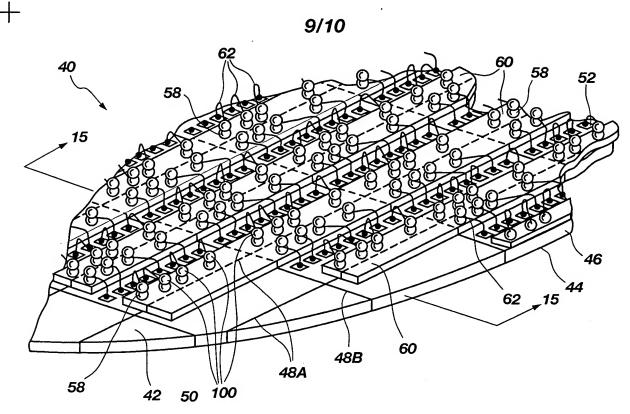
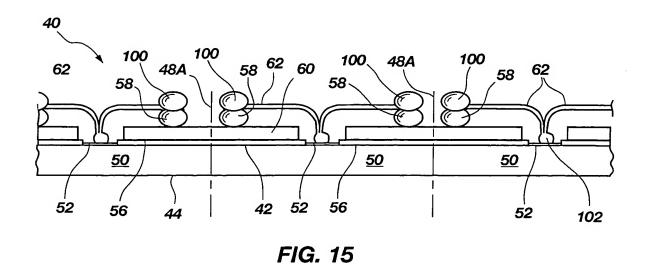


FIG. 14



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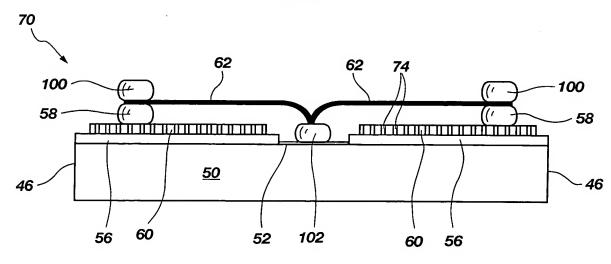


FIG. 16

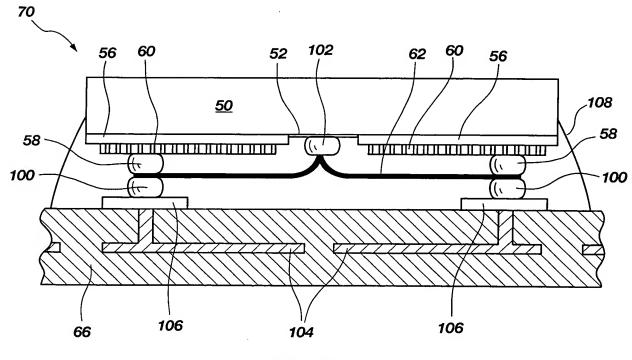


FIG. 17